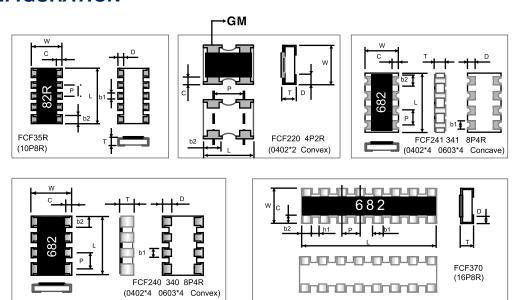
FEATURES

High density packaging provides higer productivity. Stable convex terminal reduces assembly costs. Compatible with flow and reflow soldering.

APPLICATIONS

- Computer
- Portable audio
- Mobile phone
- Battery charger
- Camcorder
- Hard Disk Driver

CONFIGURATION



DIMENSIONS

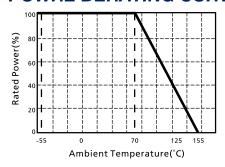
TYPE	L	W	Т	С	D	Р	b1	b2	h1
FCF220	1.00±0.10	1.00±0.10	0.35±0.10	0.20±0.15	0.25±0.17	0.65±0.10	-	0.34±0.10	-
FCF240	2.00±0.10	1.00±0.10	0.45±0.10	0.20±0.10	0.25±0.10	0.50±0.05	0.30±0.05	0.40 ± 0.10	-
FCF241	2.00±0.10	1.00±0.10	0.45±0.10	0.20±0.15	0.25±0.10	0.50±0.05	0.25±0.05	0.25 ± 0.05	
FCF340	3.20±0.20	1.60±0.10	0.50±0.10	0.30±0.20	0.30±0.20	0.80±0.10	0.45±0.10	0.60±0.15	-
FCF341	3.20+0.20/-0.10	1.60+0.20/-0.10	0.60±0.10	0.35±0.15	0.50±0.15	0.80±0.10	0.50±0.15	0.60±0.15	
FCF35R	3.30±0.20	1.60±0.1.5	0.55±0.10	0.40±0.15	0.40±0.15	0.64±0.05	0.40±0.15	0.50±0.05	-
FCF370	4.00±0.20	1.60±0.15	0.45±0.10	0.30±0.20	0.30±0.20	0.50±0.20	0.30±0.10	0.40±0.20	0.20±0.10

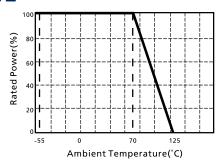
(unit: mm)





POWRE DERATING CURVE

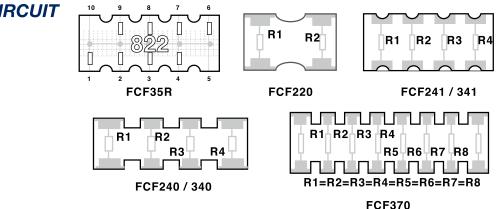




Maximum dissipation in percentage of rated power as a function of the ambient temperature for FCF220, FCF240, FCF241, FCF340, FCF341, FCF35R

Maximum dissipation in percentage of rated power as a function of the ambient temperature for FCF370

CIRCUIT



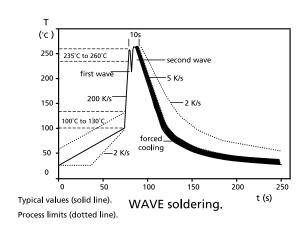
RATING

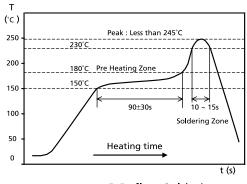
Туре	Size					Resist Range	Standard Resistance			
			at 70°C		Voltage	(%)	(TCR; ppm/°C)	Min.	Max.	Values
FCF220	4P2R 0402*2	Convex	1/16W	25V	50V	±5%(J)	±300	0Ω,10Ω	1ΜΩ	E-24
FCF240	8P4R 0402*4	Convex	1/16W	25V	50V	±5%(J) ±1%(F)	±300	0Ω,10Ω 100Ω	1MΩ 1MΩ	E-24
FCF241	8P4R 0402*4	Concave	1/16W	25V	50V	±5%(J) ±1%(F)	±300	0Ω,10Ω 10Ω	1MΩ 1MΩ	E-24
FCF340	8P4R 0603*4	Convex	1/16W	50V	100V	±5%(J) ±1%(F)	±200	0Ω,10Ω	1ΜΩ	E-24
FCF341	8P4R 0603*4	Concave	1/16W	50V	100V	±5%(J)	±200	0Ω,10Ω	1ΜΩ	E-24
FCF35R	10P8R	Convex	1/16W	25V	50V	±5%(J)	±200	10Ω	100ΚΩ	E-24
FCF370	16P8R	Convex	1/16W	25V	50V	±5%(J) ±1%(F)	±200	0Ω,10Ω 10Ω	100KΩ 100KΩ	E-24

Jumper : All networks (except FCF35R) maximum resistance Rmax < $50m\,\Omega$ and rated current $I_R \leq 1A$



SOLDERING TEMPERATURE CURVE





IR Reflow Soldering

PART NUMBER

FCF Type	340 Size	J Tolerance	T	473 Marking
туре	Size	Tolerance	Packing	iviarking
FCF	220 : 0402*2	F: ± 1% J: ± 5%	T : Paper tape - 5Kpcs	examples:
	240 : 0402*4(Convex)	J: <u>-</u> 5%	V : Paper tape - 10Kpcs	473 47x10 ³
	241 : 0402*4(Concave)		W: Paper tape - 20Kpcs	=47ΚΩ
	340 : 0603*4(Convex)			
	341 : 0603*4(Concave)			
	35R : 10P8R			
	370 : 16P8R			

RESISTANCE MARKING

E - 24 SERIES



3 digit marking for E24

examples: $473 47x10^3 = 47K\Omega$

 $10x10^5 = 1M \Omega$ 105

100 = 10 Ω

STANDARE RESISTANCE VALUE

E3	10				22				47								
E6	10		15		22		33		47		68						
E12	10	12	15	18	22	27	33	39	47	56	68	82					
F24	10	11	12	13	15	16	18	20	22	24	27	30	33	36	39	43	47
E24	51	56	62	68	75	82	91										







SPECIFICATION AND TEST METHODS

ITEM	SPECIFICATION	TEST METHOD
DC Resistance	J:±5% , F:±1% Zero ohm Jumper < 50mΩ	IEC 60115-1 / JIS C 5201-1 , Clause 4.5 Measure the resistance value.
Short time Overload	J: \triangle R ≤ ± (2% + 0.1Ω) F: \triangle R ≤ ± (1% + 0.05Ω)	IEC 60115-1 / JIS C 5201-1 , Clause 4.13 2.5X Rated voltage or Max. Overload Voltage for 5 sec. measure resistance after 30 minutes
Solderability	Over 95% of termination must be covered with solder	IEC 60115-1 / JIS C 5201-1 , Clause 4.17 After immersing flux, dip in the 235 \pm 2°C molten solder bath for 2 \pm 0.5 sec.
Resistance to Solder Heat	J: △R ≦ ± (1% + 0.1 Ω) F: △R ≦ ± (0.5% + 0.05 Ω) No mechanical damage	IEC 60115-1/JIS C 5201-1 , Clause 4.18 With 260 \pm 5°C for 10 \pm 1 sec.
Temperature Coefficient of Resistance (TCR)	Size: 0402*2,0402*4 ± 300 ppm/°C Size:0603*4,10P8R,16P8R ± 200 ppm/°C	IEC 60115-1 / JIS C 5201-1 , Clause 4.8 Test temperature : 25° C (T1) \rightarrow -55 $^{\circ}$ C (T2) 25° C (T1) \rightarrow +155 $^{\circ}$ C (T2) TCR (ppm/°C) = $\frac{R2-R1}{R1}$ x $\frac{1}{T2-T1}$ x $\frac{10^{6}}{T1:25^{\circ}}$ C T2: Test temperature
		R1: Resistance at reference temperature (T1) R2: Resistance at test temperature (T2)
Load Life Humidity	J: △R≦± (3% + 0.1Ω) F: △R≦± (1% + 0.05Ω)	IEC 60115-1 / JIS C 5201-1, Clause 4.24 Maintain the temperature of the resistor at 40±2°C and 90~95% R.H. with the rated voltage applied.Cycle ON for 1.5 hours and OFF for 0.5 hour for 1000+48/-0 hours. After 1~4 hour, measure the resistance value.
Load Life	J: △R≦± (3% + 0.1Ω) F: △R≦± (1% + 0.05Ω)	IEC 60115-1 / JIS C 5201-1 , Clause 4.25 Permanent resistance change after 1000+48/-0 hours (1.5 hours ON , 0.5 hour OFF) at RCWV or Max.Keep the resistor at 70±2°C ambient
Temperature Cycle	J: △R≦± (1% + 0.1Ω) F: △R≦± (0.5% + 0.05Ω) No mechanical damage	IEC 60115-1 / JIS C 5201-1 , Clause 4.19 Repeat 5 cycles as follows -55°C(30 min.) ~ + 25°C(2~3 min.) +125°C(30 min.) ~ + 25°C(2~3 min.) for FC370 -55°C(30 min.) ~ + 25°C(2~3 min.) +155°C(30 min.) ~ + 25°C(2~3 min.) for FCF220,FCF240,FCF241,FCF340,FCF341,FCF35R
Insulation Resistance	Between termination and coating must be over 1000M $\boldsymbol{\Omega}$	IEC 60115-1 / JIS C 5201-1 , Clause 4.6 Test voltage: 100±15V
Bending Strength	J: △R≦± (1% + 0.1Ω) F: △R≦± (0.5% +0.05Ω) No mechanical damage	IEC 60115-1 / JIS C 5201-1 , Clause 4.33 Resistance change after bended on the 90mm PCB. Bend: 1mm for FCF370 2mm for FCF220,FCF240,FCF241, FCF340, FCF341,FCF35R